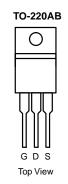


P-Channel 60-V (D-S) MOSFET

PRODU	ICT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
- 60	0.019 at V _{GS} = - 10 V	- 53	38 nC
- 00	0.026 at V _{GS} = - 4.5 V	- 42	30 110



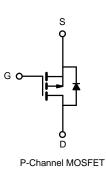
FEATURES

- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switch





Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current (T. 450 °C)	T _C = 25 °C		- 53 ^a		
	T _C = 70 °C		- 46.8		
Continuous Drain Current ($T_J = 150 \ ^\circ C$)	T _A = 25 °C	I _D	-9.2 ^b	A	
	T _A = 70 °C		- 8.1 ^b	A	
Pulsed Drain Current		I _{DM}	- 200		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 45		
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	101	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	69 ^a	^	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.1 ^b	- A	
	T _C = 25 °C		104.2 ^a		
Mariana Dissisting	T _C = 70 °C		66.7 ^a		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.1 ^b	W	
	T _A = 70 °C		2 ^b		
Operating Junction and Storage Temperature Ra	ange	TJ, T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C/W
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2	0/00

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$,	unless othe	erwise noted)				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		68		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	2		- 5.2		IIIV/ C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Cata Valtaga Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	IDSS	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μA
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α
	Р	V _{GS} = - 10 V, I _D = - 30 A		0.019		0
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 20 A		0.026		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			S
Dynamic ^b						1
Input Capacitance	C _{iss}			3500		
Output Capacitance	C _{oss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		390		pF
Reverse Transfer Capacitance	C _{rss}			290		
Tatal Oata Obarra		$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -55$ A		76	115	
Total Gate Charge	Qg			38	60	
Gate-Source Charge	Q _{gs}	$V_{DS} = -30$ V, $V_{GS} = -4.5$ V, $I_{D} = -55$ A		16		nC
Gate-Drain Charge	Q _{gd}			19		
Gate Resistance	Rg	f = 1 MHz		5.2		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	V_{DD} = - 2 V, R _L = 2 Ω		7	15	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		70	110	ns
Fall Time	t _f			40	60	
Drain-Source Body Diode Characteristic	s					1
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 69	•
Pulse Diode Forward Current ^a	I _{SM}				- 150	A
Body Diode Voltage	V _{SD}	I _S = - 30 A		- 1	- 1.5	V
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns
Body Diode Reverse Recovery Charge	Q _{rr}			59	120	nC
Reverse Recovery Fall Time	t _a	I _F = - 50 A, di/dt = 100 A/μs, T _J = 25 °C		29		
Reverse Recovery Rise Time	t _b	1		16	ł	ns

emi

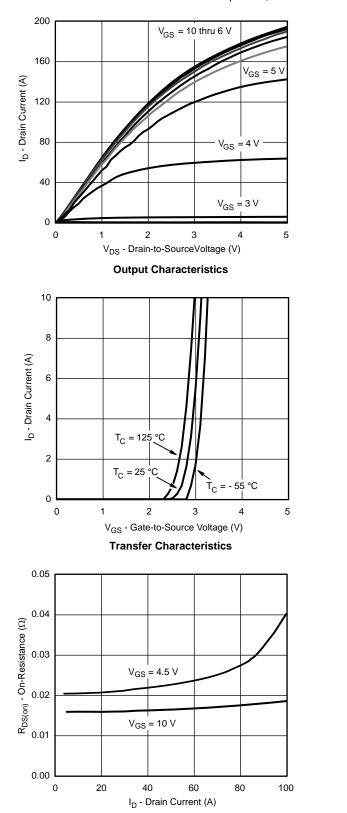
Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

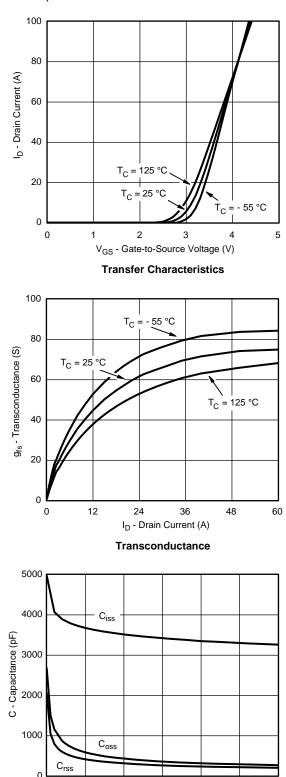
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

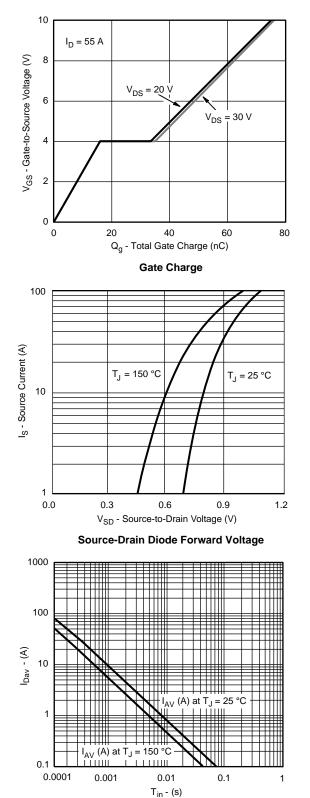




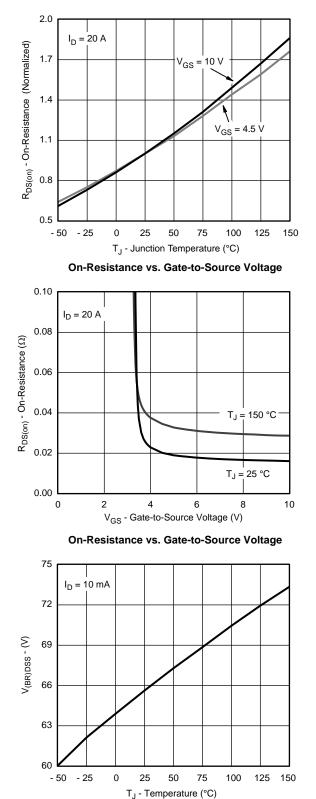




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

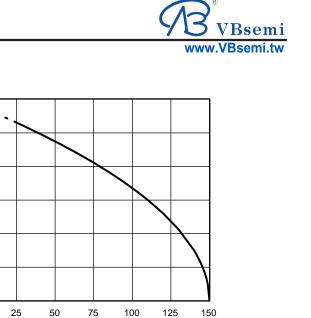


Single Pulse Avalanche Current Capability vs. Time

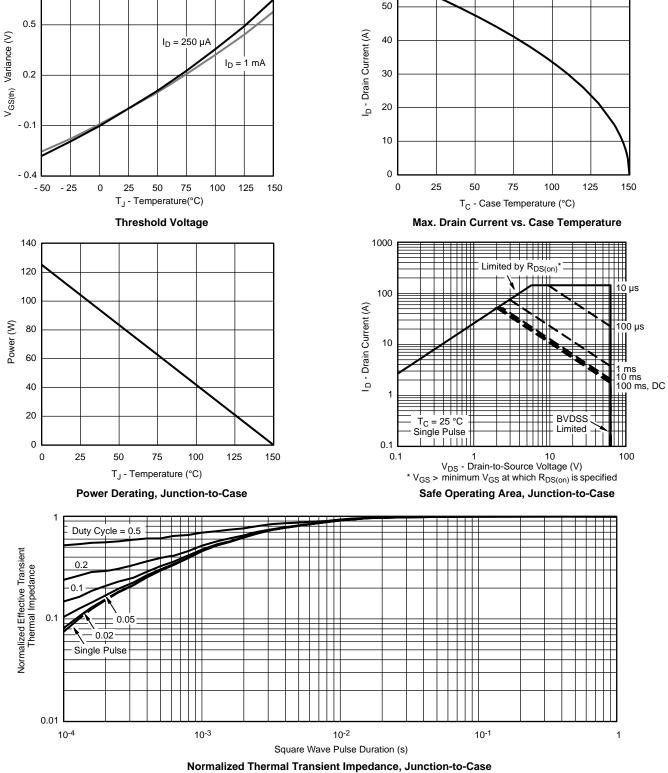


Drain-Source Breakdown Voltage vs. Junction Temperature

0.8



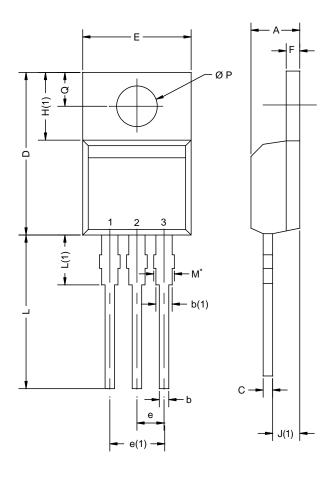
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



60



TO-220AB



MIN. 4.25 0.69 1.20 0.36 14.85 10.04 2.41 4.88	MAX. 4.65 1.01 1.73 0.61 15.49 10.51 2.67 5.28	MIN. 0.167 0.027 0.047 0.585 0.395 0.095	MAX 0.183 0.040 0.068 0.024 0.610 0.414 0.105
0.69 1.20 0.36 14.85 10.04 2.41	1.01 1.73 0.61 15.49 10.51 2.67	0.027 0.047 0.014 0.585 0.395 0.095	0.040 0.068 0.024 0.610 0.414 0.105
1.20 0.36 14.85 10.04 2.41	1.73 0.61 15.49 10.51 2.67	0.047 0.014 0.585 0.395 0.095	0.068 0.024 0.610 0.414 0.105
0.36 14.85 10.04 2.41	0.61 15.49 10.51 2.67	0.014 0.585 0.395 0.095	0.024 0.610 0.414 0.105
14.85 10.04 2.41	15.49 10.51 2.67	0.585 0.395 0.095	0.610 0.414 0.105
10.04 2.41	10.51 2.67	0.395	0.414
2.41	2.67	0.095	0.105
	-		
4.88	5.28	0.400	
	5.20	0.192	0.208
1.14	1.40	0.045	0.055
6.09	6.48	0.240	0.255
2.41	2.92	0.095	0.115
13.35	14.02	0.526	0.552
3.32	3.82	0.131	0.150
3.54	3.94	0.139	0.155
2.60	3.00	0.102	0.118
	2.41 13.35 3.32 3.54 2.60	2.41 2.92 13.35 14.02 3.32 3.82 3.54 3.94	2.41 2.92 0.095 13.35 14.02 0.526 3.32 3.82 0.131 3.54 3.94 0.139 2.60 3.00 0.102

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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